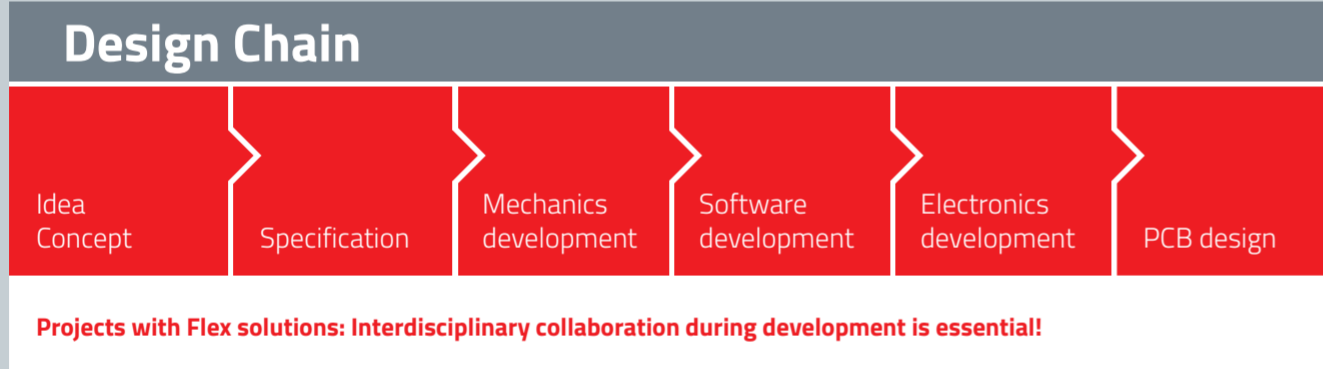


FLEX SOLUTIONS AVANT-GARDE

Technology variants		
PURE.flex	SLIM.flex	STRETCH.flex
<p>PURE.flex 2F</p> <p>PURE.flex 2F-Ri (with stiffener)</p> <ul style="list-style-type: none"> Very thin flex film polyimide Up to two copper layers Partially reinforced by „stiffener“ Photosensitive solder mask or cover foil (Polyimide Coverlay) Delivered individually or as panel array <p>Number of copper layers: 1 to 2</p>	<p>SLIM.flex 4F-Ri in Anylayer microvia technology</p> <ul style="list-style-type: none"> Anylayer microvia flex technology Very thin Highly resilient, robust Flexible and reliable Impedance-defined structure possible Optionally with solder carrier and stiffener <p>Applications</p> <ul style="list-style-type: none"> Vision technologies Medical technologies Sensor technologies High-tech cable harness <p>Number of copper layers: 3 to 8</p>	<p>STRETCH.flex 15-Ri</p> <ul style="list-style-type: none"> Stretchable circuit carriers made of thermoplastic polyurethane Conductors in e.g. meander or snake shape for extreme flexibility Dynamic extensibility depending on design from 5 – 20%. Almost any shape can be realized Skin friendly Can be combined with textiles Thermoformable <p>Number of copper layers: 1 to 2</p>



MECHANICS

- Always provide large contour radii (inner and outer radii) in the flex areas (design suitable for plastics)
- If necessary, provide registration holes for bonding reinforcements or heatsinks
- Arrange flex extensions to save space, combine several extensions if possible, use folding technology

Standard Stackups

<p>PURE.flex https://www.we-online.com/pureflex-stackups</p>	<p>SLIM.flex https://www.we-online.com/slimflex-stackups</p>	<p>STRETCH.flex https://www.we-online.com/stretchflex-stackups_en</p>
--	--	---

Combination with other technologies

It is possible to combine flex solutions with other technologies, for example with

- High Density Interconnect MICROVIA.hdi
- DEVICE.embedding
- Printed Polymer
- Heatsink

Adaptation of the individual design rules is usually necessary for this purpose.

PCB Design

Design Rules

Our Design Rules cover all the important parameters you need to make your project successful. Basically, the rules for conductor widths, distances, via and pad sizes as well as for the solder mask apply, which you can find in our BASIC Design Rules.

https://www.we-online.com/designrulesbasic_en

Based on this, the sectional design rules apply for

- PURE.flex (https://www.we-online.com/designrulespureflex_en)
- SLIM.flex (https://www.we-online.com/designruleslimflex_en)
- STRETCH.flex (https://www.we-online.com/designrulesstretchflex_en)

https://www.we-online.com/designguideflex_en

In our Design Guide for Flex Solutions you will find an overview of all variants of our flex solutions plus some valuable design tips to bring your application to success, reliably and safely.

SLIM.flex – Any layer microvia technology

Example: SLIM.flex 6F

left: schematic stackup 0.30 mm thick
right: cross sectional picture from a product

left: BGA pitch 0.40 mm with microvia-in-pad, flat surface
right: BGA pitch 0.35 mm in the EDA tool

STRETCH.flex – Stretchable PCB Substrate

Meander-Structure

Different meander structures lead to extreme flexibility of the printed circuit board. A combination of meander structure and layout allows dynamic stretchability between 5 – 20%.

Wave-Meander-Structure, Horseshoe-Meander-Structure, Rectangle-Meander-Structure

Dynamic stretch and FR4 Stiffener

FR4 Stiffener (shown on an 15-0Ri)

ORDER HAND SAMPLE FREE OF CHARGE

SLIM.flex
Hand Sample WE.scope
<https://www.we-online.com/wescope>

STRETCH.flex
Hand Sample WE.band
<https://www.we-online.com/weband>

HOTLINE TO OUR „FLEXPERTS“

Phone +49 7940 946-FLEX (3539)
flex@we-online.com
stretch@we-online.com